Momentive’s thermally conductive gap fillers are non-slumping, dispensable materials that can be applied to gaps to create a heat path. These non-adhesive curing type TIMs form a soft, stress-absorbing thermal interface. In addition to filling gaps in electronic components, they can be applied to flat or high-profile 3-dimentional surfaces as a cure-in-place thermal pad or as a pump-out resistant alternative to greases.

Key Features of Momentive's Thermal Gap Fillers

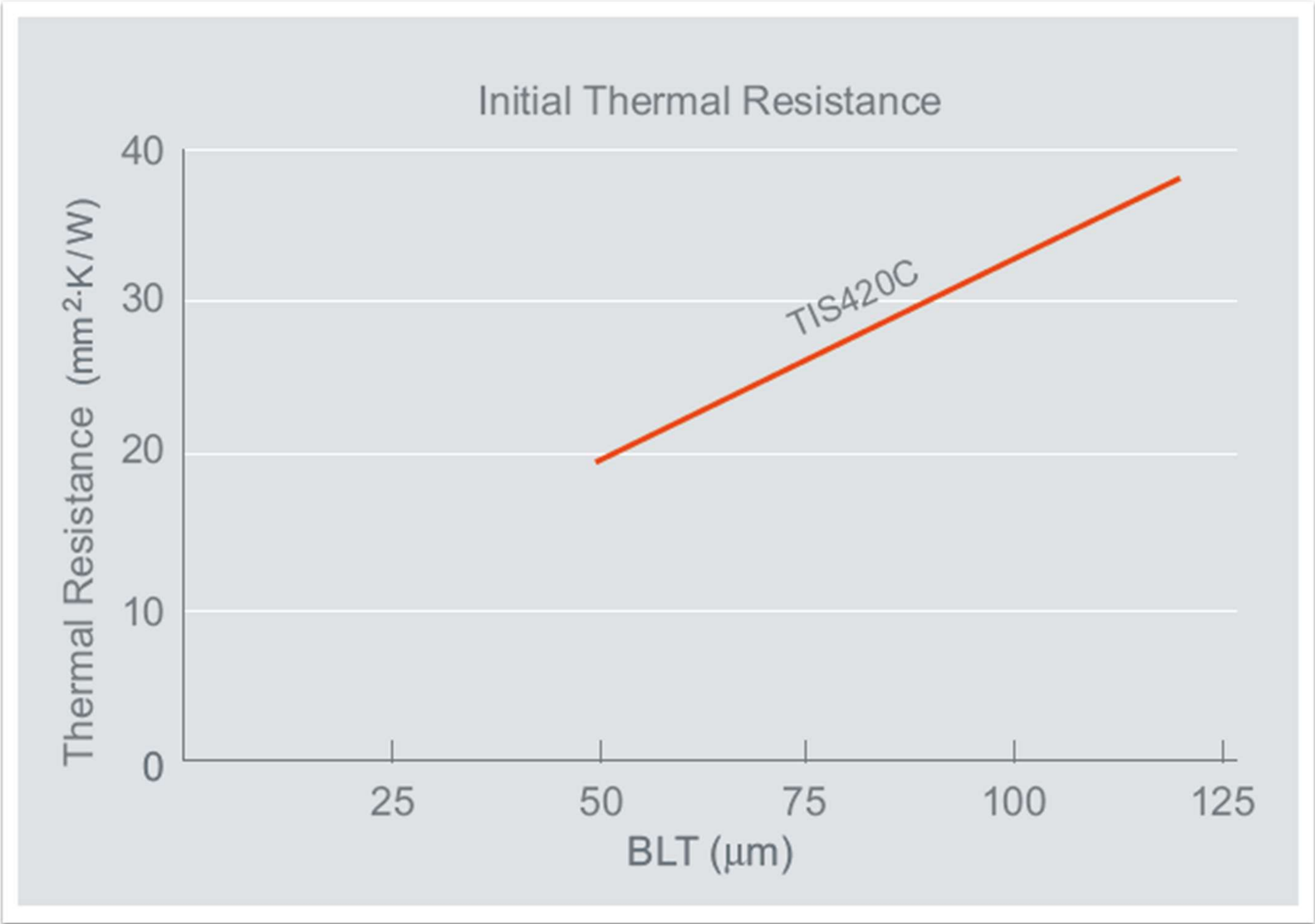
- Good thermal conductivity
- Fast, low temperature cure
- Helps provide stress relief during thermal cycling
- Conforms to complex, 3-dimensional designs
- Non-adhesive, repairable

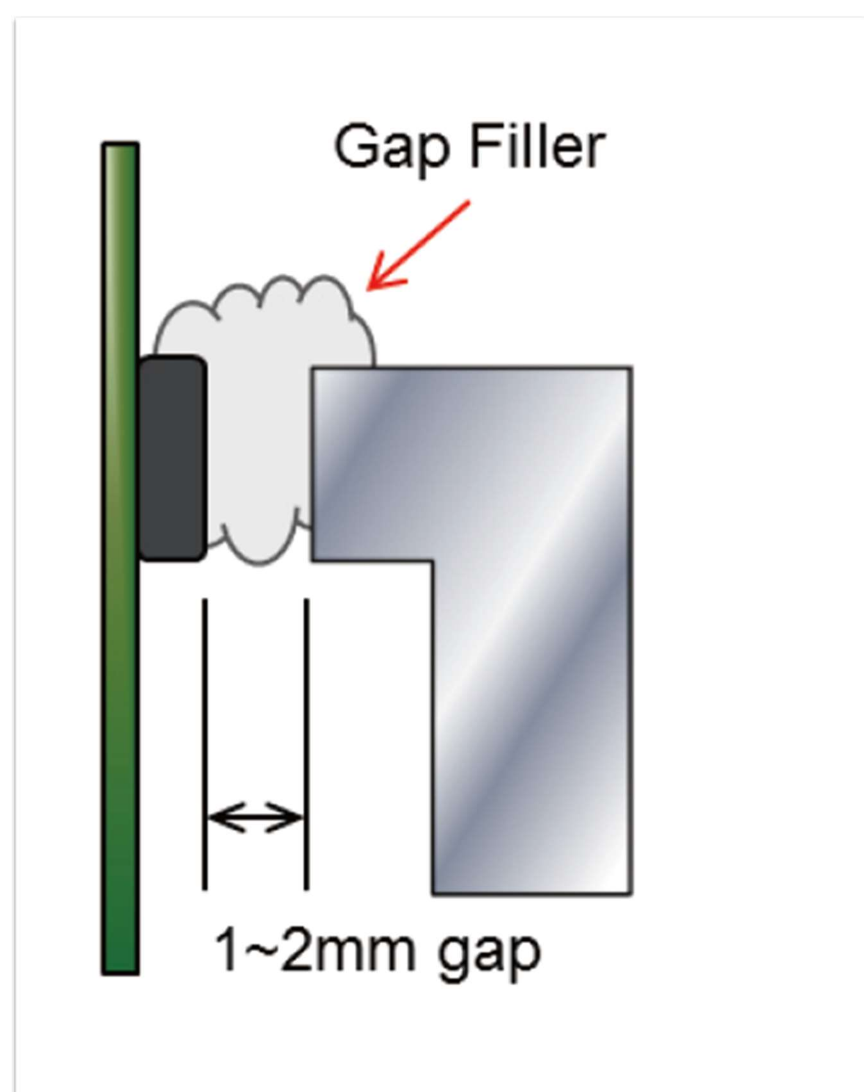
Product Details

Properties		TIS420C	TIA225F	TIA241GF
Mixing Ratio ((A):(B) by weight)		-	100:100	100:100
Property (uncured)		Non-Flowable	Non-Flowable	Non-Flowable
Color		Gray	Gray	Blue
Viscosity (23°C)	Pa.s	300	90	130
Workable Life (23°C)	h	-	4	3
Tack Free Time	min	30	-	-
Cure Condition (heat)	°C/h	-	70/0.5	70/0.5
Specific Gravity (23°C)		3.2	2.9	3.14
Thermal Conductivity[1]	W/m.K	4.2	2.5	4.1
Thermal Resistance[2] (BLT)	mm2.K/W	20 (50μm)	35 (50μm)	30 (80μm)
Volume Resistivity	MΩ.m	$3.0x10^3$	$6.0x10^6$	$1.0x10^4$
Volatile Siloxane (D4-D10)	ppm	100	200	150

[1]Hot wire method, [2]Laser flash analysis on Si-Si sandwiched material

Typical property data values should not be used as specifications


Initial Thermal Resistance
Thermal Resistance (mm²·K/W)
40
30
20
10
0
TIS420C
25
50
75
100
125
BLT (µm)


Gap Filler
1~2mm gap